SURFACE MOUNT ULTRAFAST RECOVERY RECTIFIER

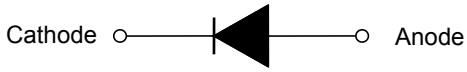
FEATURES:

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High efficiency
- Lead free in comply with EU RoHS 2011/65/EU directives

Marking

Type number	Marking code
US1A	US1A
US1B	US1B
US1D	US1D
US1G	US1G
US1J	US1J
US1K	US1K
US1M	US1M

Circuit Diagram & Pin Configuration:



SMA/DO-214AC

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T_c = 125 °C	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30							A
Maximum Instantaneous Forward Voltage at 1 A	V_F	1.0			1.3	1.65			V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =125 °C	I_R	5 100							μA
Maximum Reverse Recovery Time (1)	t_{rr}	50				75			ns
Typical Thermal Resistance (2)	$R_{\theta JA}$	75							°C/W
Typical Junction Capacitance (3)	C_j	15							pF
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

(1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A.
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.
(3) Measured at 1 MHz and applied reverse voltage of 4 V D.C

Fig.1 Forward Current Derating Curve

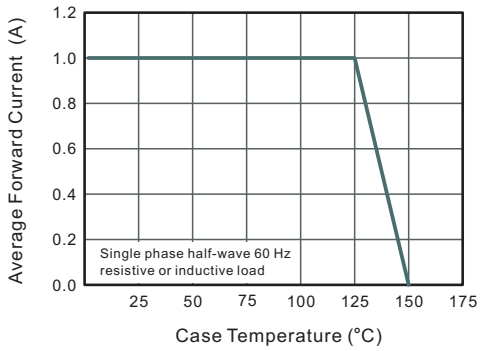


Fig.2 Typical Reverse Characteristics

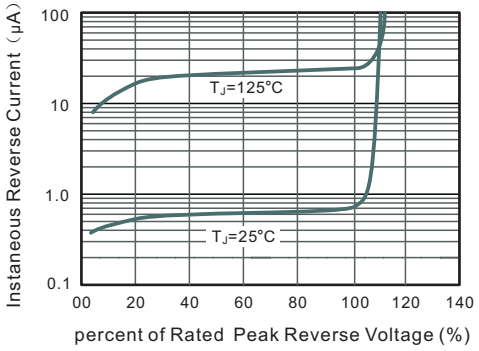


Fig.3 Typical Forward Characteristics

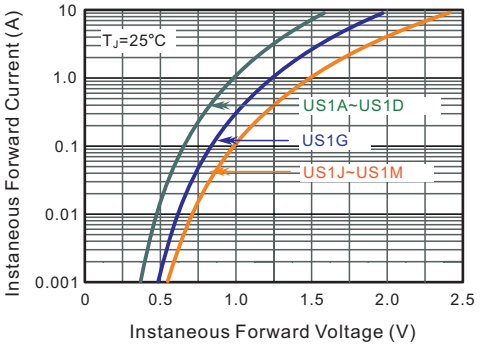


Fig.4 Maximum Non-Repetitive Peak Forward Surage Current

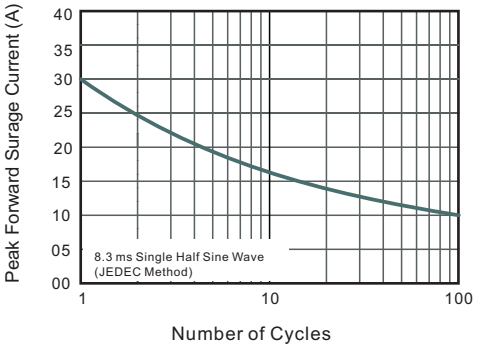


Fig.5- Typical Transient Thermal Impedance

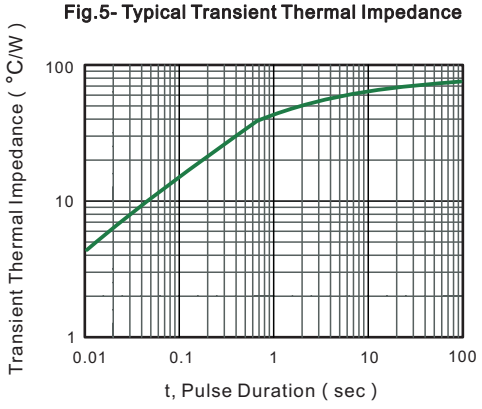
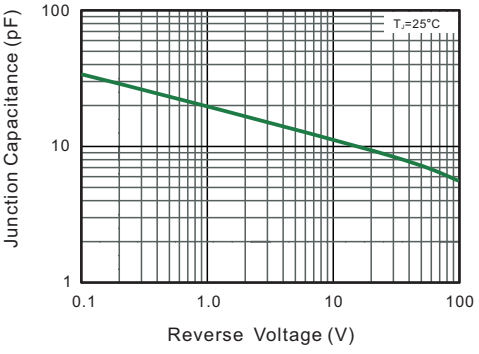
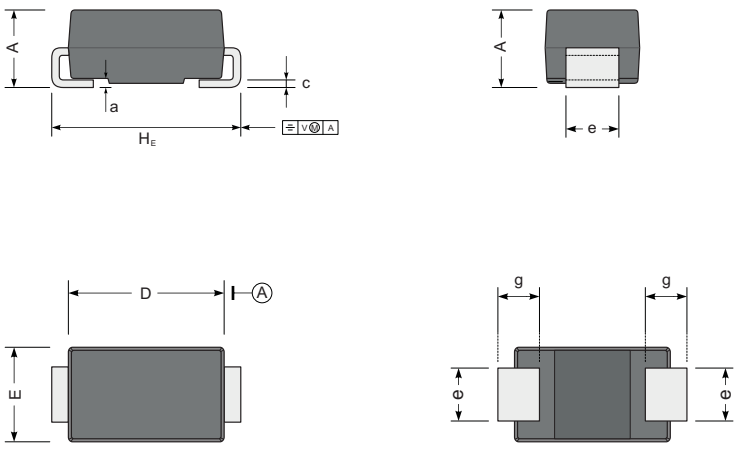


Fig.6 Typical Junction Capacitance



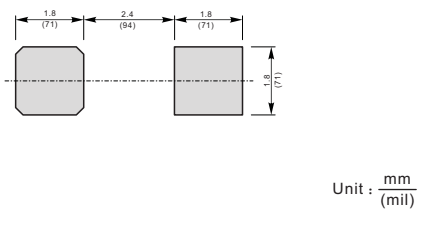
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads **SMA/DO-214AC**



UNIT		A	D	E	H_E	c	e	g	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	
mil	max	87	181	106	205	12	63	59	12
	min	75	157	91	185	6	51	35	

The recommended mounting pad size



NOTICE

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